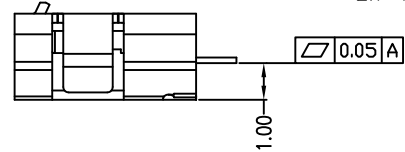
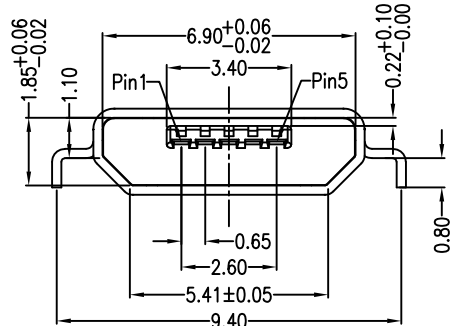
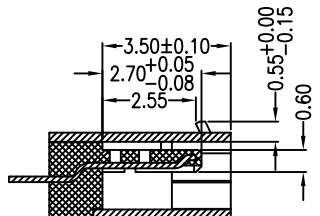
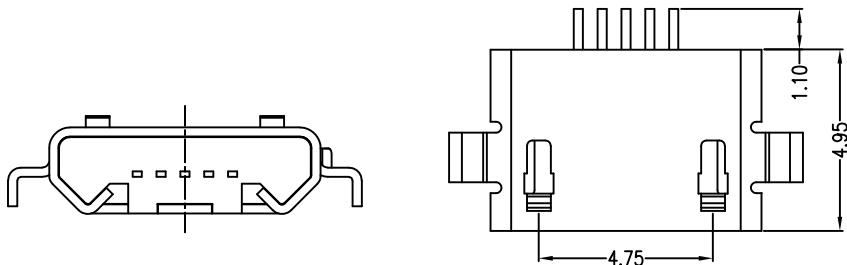
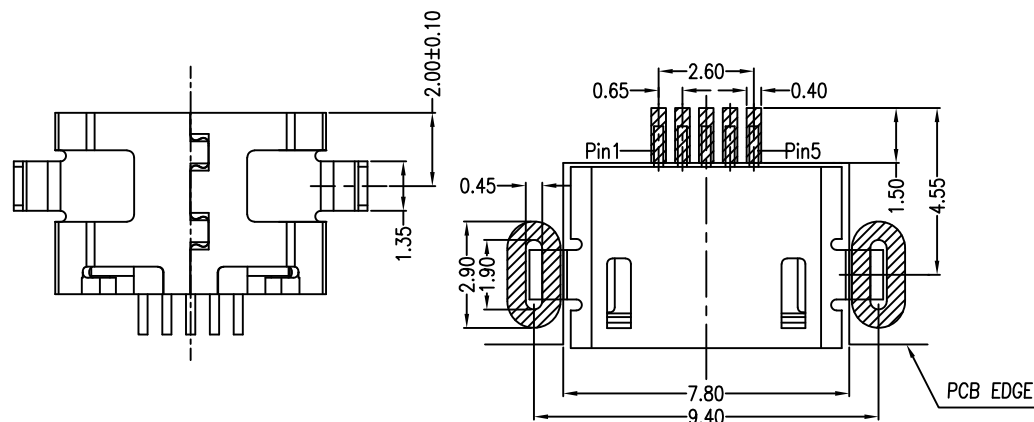


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE



Note:  
 1.Material:  
 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0  
 1.2 Contact: copper alloy,t=0.15mm  
 1.3 Shell: copper alloy,t=0.25mm  
 2.Specification:  
 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.  
 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.  
 2.3 Contact resistance: 30 mΩ Max.  
 2.4 Insulation resistance: 100 MΩ Min.  
 2.5 Total mating force: 3.57 Kgf Max.  
 2.6 Total unmating force: 1.0 Kgf Min.  
 2.7 Temperature range: -30°C~80°C



RECOMMENDED PCB LAYOUT  
 PCB图仅供参考

PART NO:		MATERIAL: SEE NOTE	深圳市创勤电子有限公司 SHENZHEN CHUANGQIN ELECTRONICS CO., LTD.	
MODEL NO: XX		FINISH: SEE NOTE	TITLE: Micro usb 5s B Type DIP 脚沉板1.0无导位	
UNIT: MM	SIZE: A4	COLOR: SEE NOTE	DWG NO: CQ067-MFCB05010114	REV: A
TOLERANCE UNSPECIFIED		DR: LINYUN	SCALE: 5:1	
.x	0.15	CHK: LJY	DATE: 2012.05.04	
.xx	0.10	APP: ZHANG		
.xxx	0.05			
Ang.	1°			

